GIGABYTE™

G363-ZR0-AAX4

HPC/AI Server - 3U DP NVIDIA HGX™ H200 4-GPU

NVIDIA® | AMD EPYC

Features

- NVIDIA HGX™ H200 4-GPU
- 4th-generation NVIDIA® NVLink® 900GB/s
- Dual AMD EPYC™ 9005/9004 Series Processors
- 12-Channel RDIMM DDR5, 24 x DIMMs
- Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Broadcom® BCM57416
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x 2.5" Gen5 NVMe hot-swap bays
- 1 x M.2 slot with PCIe Gen4 x4 interface
- 6 x LP PCIe Gen5 x16 slots
- 2+1 3000W 80 PLUS Titanium redundant power supplies

Application

AI, AI Inference, AI Training, High-Performance Computing

Specification

Dimensions	3U (W448 x H130 x D800 mm)	**I/O ports**	Front: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN (default) Rear: 2 x RJ45
Motherboard	MZ83-HD1	**TPM**	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, Socket SP5 cTDP up to 400W	**Backplane Board**	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Chipset	System on Chip	**Power Supply**	2+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord.
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs [EPYC 9005] Up to 6000 MT/s [EPYC 9004] Up to 4800 MT/s	**System Management**	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
LAN	Front: 2 x 1Gb/s LAN (1 x Intel® I350-AM2) - Support NCSI function 1 x 10/100/1000 management LAN Rear: 2 x 10Gb/s LAN (1 x Broadcom® BCM57416)	**OS Support**	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	**System Fans**	7 x 80x80x80mm (17,000rpm)
Storage	Front hot-swap: 4 x 2.5" Gen5 NVMe 4 x 2.5" Gen5 NVMe/SATA/SAS-4 *SAS card is required to support SAS drives. Internal M.2: 1 x M.2 (2280/22110), PCIe Gen4 x4	**Operating Properties**	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
RAID	Require RAID add-in cards	**Packaging Content**	1 x G363-ZR0-AAX4, 2 x CPU heatsinks, 1 x L-shape Rail kit, 1 x Mini-DP to D-Sub cable Packaging Dimensions: 1176 x 782 x 295 mm
Modular GPU	NVIDIA HGX™ H200 with 4 x SXM GPUs	**Part Numbers**	Barebone w/ NVIDIA module: 6NG363ZR0DR000ACX4* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - RMA packaging: 6NG363ZR0SR-RMA-A100
Expansion Slots	Front: 2 x LP PCIe Gen5 x16 slots Rear: 4 x LP PCIe Gen5 x16 slots (with PCIe switches)		

Learn more at **https://www.GIGABYTE.com/enterprise**

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